



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISZ08YN10NM6	Issued	07. February 2022
MA#	MA005410417		
Package	PG-TSDSON-8-34	Weight*	35.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.734	2.04	2.04	20392	20392
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		100	
	non noble metal	zinc	7440-66-6	0.014	0.04		401	
	non noble metal	iron	7439-89-6	0.288	0.80		8013	
	non noble metal	copper	7440-50-8	11.710	32.54	33.39	325368	333882
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	766	766
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		969	
	plastics	epoxy resin	-	1.797	4.99		49917	
	inorganic material	silicondioxide	60676-86-0	15.611	43.37	48.46	433743	484629
leadfinish	non noble metal	tin	7440-31-5	0.395	1.10	1.10	10982	10982
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	564	564
solder	non noble metal	tin	7440-31-5	0.020	0.05		547	
	noble metal	silver	7440-22-4	0.025	0.07		684	
	non noble metal	lead	7439-92-1	0.940	2.61	2.73	26119	27350
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			36	
	non noble metal	iron	7439-89-6	0.004	0.01		119	
	non noble metal	copper	7440-50-8	4.267	11.86	11.87	118567	118722
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.097	0.27	0.27	2709	2713
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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